SPECIFICATION FOR LCD MODULE

MODULE NO: YB-TG240320S25A-N-A1

Doc.Version:03

Customer Approval:	
Accept	☐ Reject

YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	摇芳璋	2015, 2,5
Check	Mechanical Engineer	涿振葉	2015. 3.5
Verify		套点数	7015.25
Approval		建晨后	2015,25

☐ APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-C

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1. Revision History

Sample Version	DOC. Version	DATE		DESCRIPTION	CHANGED BY
A0	00	2014-11-05	SPEC ONLY	First issue	Fanny/Aiching
A0	01	2014-12-18	FULL SPEC	First Sample	Fanny/Jimmy
A1	02	2015-01-13	FULL SPEC	Change Polarizer supplier	Fanny/Jimmy
A1	03	2015-02-05	FULL SPEC	Modi fy LCM drawingP.5	Fanny/Ujl
					<u> </u>



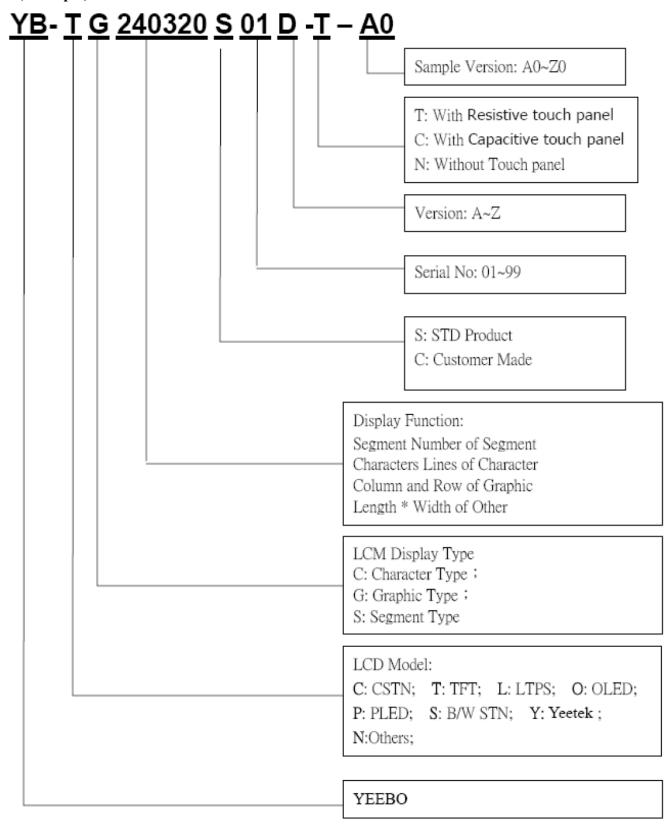
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3. Module Numbering System:

(Example)



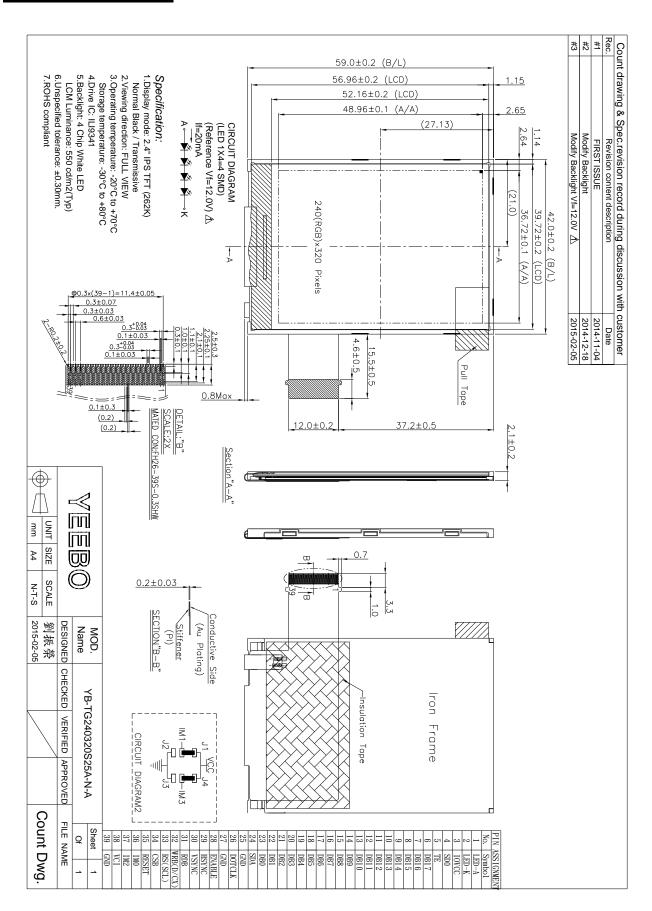


4. General Specification:

ITEM	CONTENTS				
Module Size	42.0 (W) * 59.0 (H) * 2.1 (T) mm				
Module Size(With FPC)	57.5 (W) * 59.0 (H) * 2.1 (T) mm				
Display Size(Diagonal)	2.4 inch				
Display Format	240(RGB)*320 Pixels				
Active Area	36.72(W) * 48.96 (H) mm				
Pixel Pitch	0.153 * 0.153 mm				
LCD Type	TFT (262K) / Transmissive / Normally Black				
View Angle	Free				
Controller IC	ILI9341				
Weight	10.8g				



5. LCM drawing:





6. Electrical Characteristics

6-1 Absolute Maximum Ratings

(Ta=25°C VSS=0V)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Supply Voltage	V_{CI}	-0.3	-	+4.6	Volt	Note1
Supply Voltage(Logic)	IOV_{CC}	-0.3	-	+4.6	Volt	Note1
Operating Temperature	Topr	-20	-	+70	$^{\circ}\!\mathbb{C}$	-
Storage Temperature	Tstg	-30	-	+80	$^{\circ}\!\mathbb{C}$	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-2 Operating Conditions

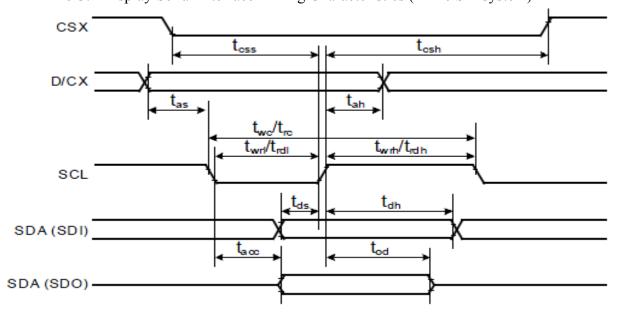
(Ta=25°C)

1					•	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply voltage	V_{CI}	-	2.6	2.8	3.0	Volt
Supply voltage for I/O	IOV _{CC}	1	1.65	2.8	3.0	Volt
Input Voltage	V_{IH}	1	0.7 * IOV _{CC}	1	IOV_{CC}	V
	V_{IL}	-	Vss	ı	0.3* IOV _{CC}	V
Power Supply Current for LCM	Icc	VCI=2.8V	-	12.0	1.0	mA



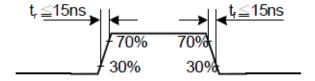
6-3 Timing Characteristics

6-3.1 Display Serial Interface Timing Characteristics (4-line SPI system)

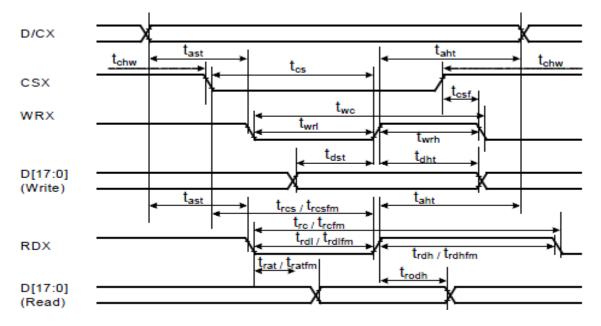


Signal	Symbol	Parameter	min	max	Unit	Description
CSX tcss		Chip select time (Write)	40	-	ns	
COA	tcsh	Chip select hold time (Read)	40	-	ns	
	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
SCL	twrl	SCL "L" pulse width (Write)	40	-	ns	
SCL	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-		
DICX	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI	tds	Data setup time (Write)	30	-	ns	
(Input)	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
(Output)	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

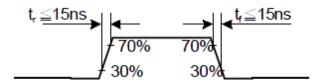






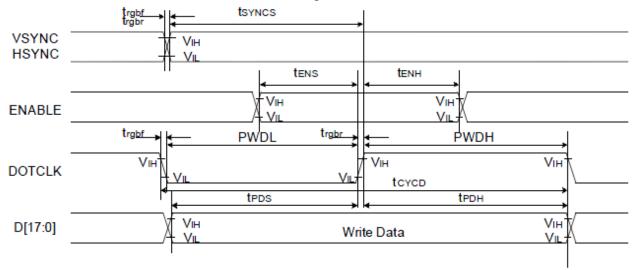
Signal	Symbo	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
DCX	taht	Address hold time (Write/Read)	0	-	ns	
	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
WRX	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D(47-0)	tdst	Write data setup time	10	-	ns	
D[17:0], D[17:10]&D[8:1],	tdht	Write data hold time	10	-	ns	For maximum CL=30pF
D[17:10]&D[6:1],	trat	Read access time	-	40	ns	For minimum CL=30pF
D[17:10], D[17:9]	tratfm	Read access time	-	340	ns	For minimum CL-ope
D[17.9]	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, \overline{VC} I=2.5V to 3.3V, \overline{VS} S=0V.



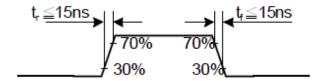


6-3.3 Parallel 18/16/6-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter		max	Unit	Description
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	t _{synch}	VSYNC/HSYNC hold time	15	-	ns	
DE	t _{ENS}	DE setup time	15	-	ns	
DE	t _{ENH}	DE hold time	15	-	ns	
D[47:0]	teos	Data setup time	15	-	ns	18/16-bit bus RGB
D[17:0]	t _{PDH}	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level period	15	-	ns	
DOTCER	toyop	DOTCLK cycle time	100	-	ns	
	t _{rgbr} , t _{rgbr}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	tsynch	VSYNC/HSYNC hold time	15	-	ns	
DE	tens	DE setup time	15	-	ns	
DE	t _{ENH}	DE hold time	15	-	ns	
D[47:0]	teos	Data setup time	15	-	ns	6-bit bus RGB
D[17:0]	t _{PDH}	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level pulse period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level pulse period	15	-	ns	
DOTOLK	tcyco	DOTCLK cycle time	50	-	ns	
	t _{rgbr} , t _{rgbr}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V





7. Optical Characteristics:

Itom		Crushal	Canditions	Specifications			T1:4	Note
Item		Symbol	Conditions	Min	Тур	Max	Unit	Note
Transmittance (With PL)		T(%)	_	-	4.65	-	-	-
Contrast Ratio		CR	⊖=0 Normal Viewing angle	-	800	-		(1)(2)
Response	e time	TR+TF	_	-	35	-	ms	(1)(3)
	Hor	Өх+		-	80	-		
Viewing Hor		Өх-	CR≧10	-	80	-	deg.	
angle	angle Ver		CK=10	-	80	-		-
	vei	Өу-		-	80	-		

Measuring Condition

1. Measuring surrounding: dark room

2. Ambient temperature: 25±2°C

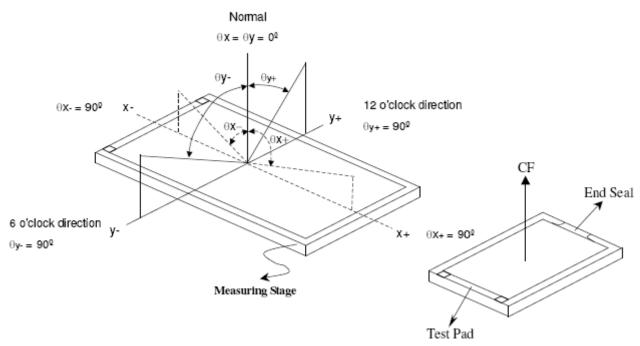
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.	Brightness
	D 1	X		0.597	0.647	0.697	100 1/ 2
	Red	у	$\theta = \phi = 0_{\circ}$	0.267	0.317	0.367	100 cd/m^2
	G	X	LED Backlight	0.265	0.315	0.365	450 cd/m ²
Chromaticity	Green	у	Color Degree	0.532	0.582	0.632	430 CQ/III ²
Coordinates (Transmissive)		X	x=0.3 y=0.3	0.090	0.140	0.190	35 cd/m ²
(Transmissive)	Blue	y	y=0.5 Brightness	0.038	0.088	0.138	33 ca/m ²
	***	X	$= 7000 \text{ cd/m}^2$	0.260	0.310	0.360	550 cd/m ²
	White	y	, 555 CG /III	0.286	0.336	0.386	330 cd/m²



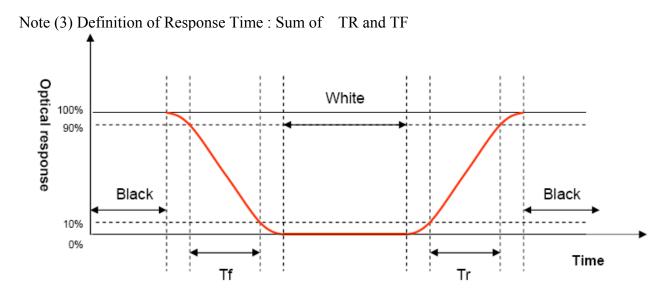
Note (1) Definition of Viewing Angle:



Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black





8. Interface Pin Assignment:

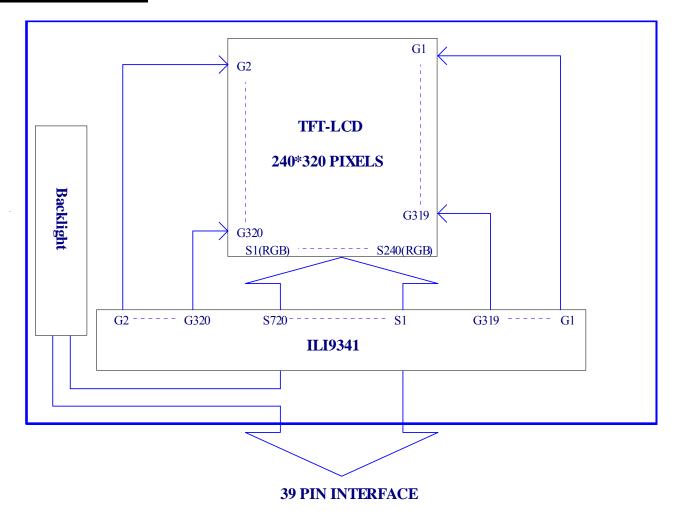
No.	Symbol	Function
1	LED_A	LED power anode
2	LED_K	LED power catHode
3	IOVCC	Digital power supply
4	SDO	Serial data output signal
5	TE	Tearing effect output pin (No connection)
6	DB17	Data bus
7	DB16	Data bus
8	DB15	Data bus
9	DB14	Data bus
10	DB13	Data bus
11	DB12	Data bus
12	DB11	Data bus
13	DB10	Data bus
14	DB9	Data bus
15	DB8	Data bus
16	DB7	Data bus
17	DB6	Data bus
18	DB5	Data bus
19	DB4	Data bus
20	DB3	Data bus
21	DB2	Data bus
22	DB1	Data bus
23	DB0	Data bus
24	SDA	Serial data input signal
25	GND	Ground
26	DOTCLK	Pixel clock signal in RGB I/F mode
27	GND	Ground



28	ENABLE	Data	Data enable signal in RGB I/F mode					
29	HSYNC	Horiz	ontal	sync	c. Sig	nal in RGB I/F mode		
30	VSYNC	Vertic	cal sy	nc. S	Signa	I in RGB I/F mode		
31	RDB	Read	sign	al in	80-se	eries parallel interface		
32	WRB	Write	sign	al in	80-se	eries parallel interface		
33	RS	Data/	Com	man	d sele	ect signal		
34	CSB	CHip	sele	ct sig	nal			
35	RESET	Rese	t sigr	nal				
		Selec	t MC	U Int	terfac	e mode	DB Pin in u	se
36		IM3	IM2	IM1	IMO	MCU-Interface Mode	Register/content	GRAM
	IMO	1	0	1	0	80 MCU 18-bit bus Interface II	D[8:1]	D[17:0]
	IM2	1	0	1	1	80 MCU 9-bit bus Interface II	D[17:10]	D[17:9]
37		1	1	1	0	4-wire 8-bit data serial Interface II	SDI: in SOO: out	:
38	VCI	Analo	og po	wers	suppl	y		
39	GND	Grou	nd					



9. Block Diagram:



Module P/N:YB-TG240320S25A-N-A1 Doc.Version:03



10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

(Ta=25°C)

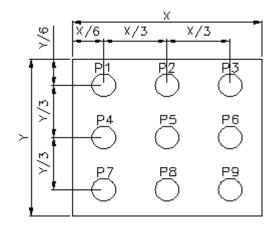
: Duta Rood EED Backinght.							
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I	ı	20	1	mA	V=12.0V	
Supply Voltage	V	11.0	12.0	13.2	V	If=20mA	
Reverse Voltage	VR	-	-	5	V	-	
Luminous Intensity for LCM	IV	450	550	ı	Cd/m2	If=20mA	2
Uniformity for LCM	-	70	-	-	%	If=20mA	3
Life Time	-	-	50000	-	Hr.	If=20mA	4
Color				Wh	ite		

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram





(Effective spatial Distribution)

Hole Diameter ø8 mm; 1 to 9 per Position Measured Luminous



11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm X,Y,Z 2 hours for each direction. Sweep time: 12 min
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ± 4 KV 150pF/330 Ω 5 times
	pla size for each test its	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5 $^{\circ}$ C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to MIL-STD105E. General Inspection Level ${\rm II}$ take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

12-3. Non- conforming Analysis & Deal With Manners

- a. Non-conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

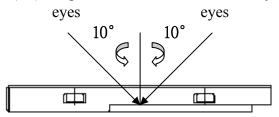
Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

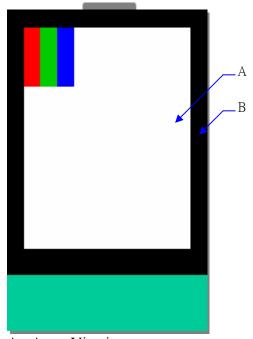


12-5. Standard of The Product Appearance Test

- a. Manner of appearance test:
- (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at $30\pm5cm$.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area.

(Outside viewing area)

- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

NO	Item	Criterion					
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 					
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	Five spots. 2.2 Densely spaced:	No more that	an three spots wi	0.25mm, no more than thin 3mm.	2.5	
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As $\Phi = (X+Y)/2$ $* De$ 3.2 Line type: (As for example of the ex	ensely space	Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$ d: No more than wing)	Accept no dense	2.5	
		* D		0.08 <w< td=""><td>Rejection two lines within 3mm.</td><td></td></w<>	Rejection two lines within 3mm.		



NO	Item	Criterion				
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ(mm) $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q'ty	Acceptable Q'ty Accept no dense 3 2 0 3	2.5	
05	Scratches	Follow NO.3 -2 Line Type.				
06	Chipped glass	L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface an $z = 1.1$ Chip on panel surface an $z = 1.1$ Chip thickness $z = 1.2$ Not on $z = 1.2$ Corner crack: $z = 1.2$ Not on $z = 1.2$ Not $z = 1.$	s thickness a: LCD side and crack between panels: width	length 1/8a 1/8a each chip	2.5	



NO	Item	Criterion					
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:					
		y: Chip width x: Chip length z: Chip thickness					
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$					
07	Glass crack	Non-conductive portion:	2.5				
		y: Chip width x: Chip length z: Chip thickness					
		$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$					
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length y≤1/3L X≤a 					



NO	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion					
NO 14	Touch Panel Chipped glass	z : Chip thickness $Z \le t$	y: Chip width z: t: Touch Panel Total t	x: Chip length x≤1/8a	side	AQL 2.5	
		z: Chip thickness $z \le t$ $\odot \text{ Unit: mm}$ $\odot \text{ If there are 2 or m}$	y: Chip width ≤ 1/2 k and not over viewing area nore chips, x is the total 1	x : Chip length $x \le 1/8a$ length of each chip			



NO	Item	Criterion	AQL		
15	Touch Panel(Fish eye、dent and bubble on film)	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5		
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5		
17	Touch Panel Linearity	Less than 2.5% is acceptable.			
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5		
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65		



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.